[0089] An integrated circuit has a metal layer that includes conductors to provide interconnectivity for components of the integrated circuit chip. The metal layer is divided into at least two sections, such that a first section has a preferred direction and the second section has a preferred wiring direction that is different from the first preferred direction. The first and second preferred directions on a single metal layer may consist of any direction. The metal layer may be divided into more than two sections, wherein each section has a preferred wiring direction. Wiring geometries for multi-level metal layers are also disclosed

Figures

IC (Top View)

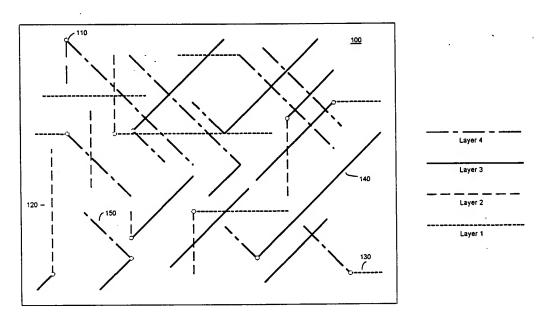


Figure 1a



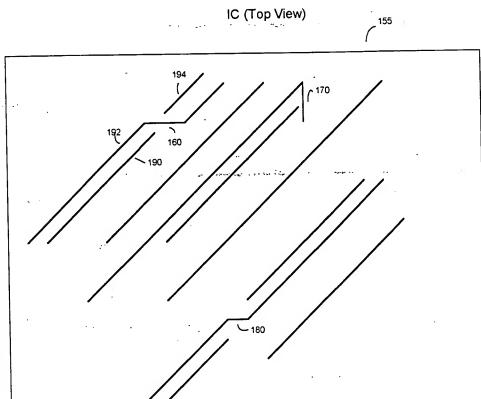
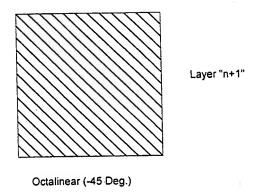
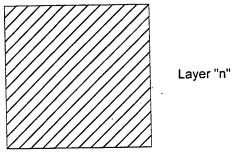


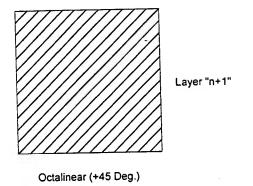
Figure 1b





Octalinear (+45 Deg.)

Figure 2a



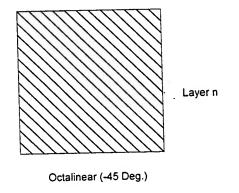
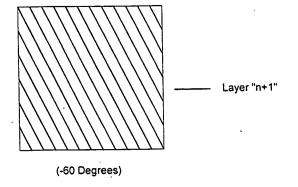


Figure 2b



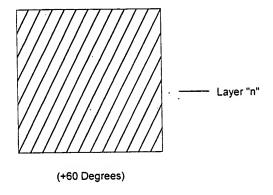
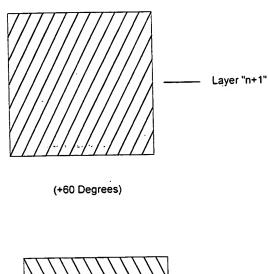
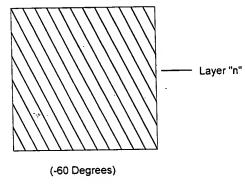


Figure 3a







loussum olluce

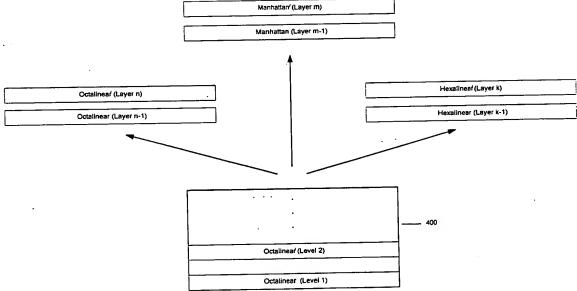


Figure 4a

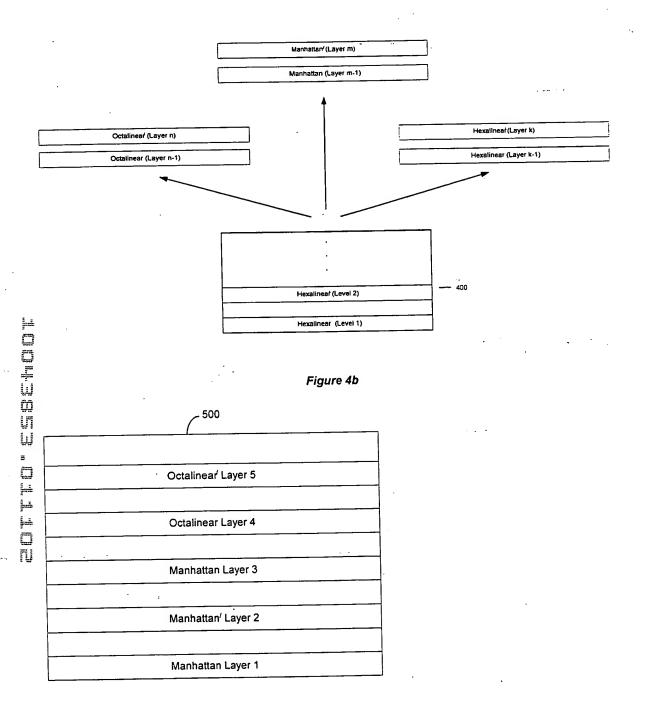


Figure 5a

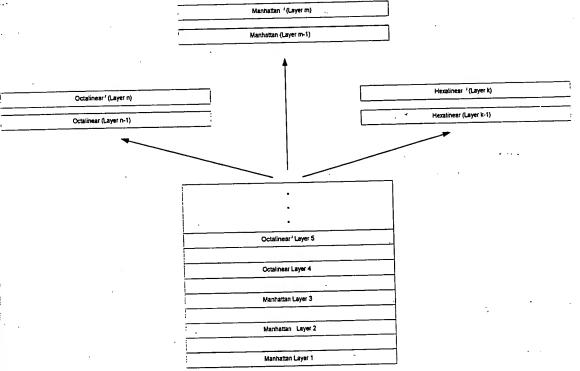
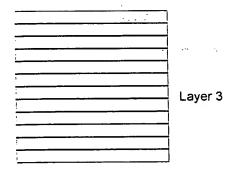
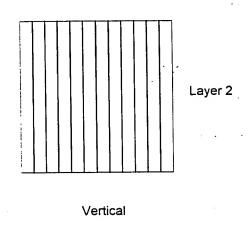
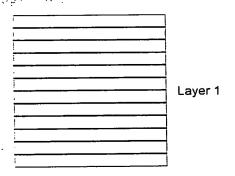


Figure 5b



Horizontal



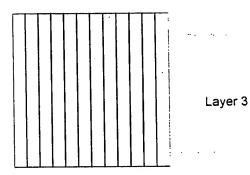


Horizontal

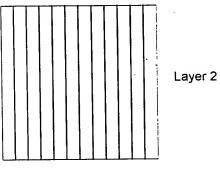
Figure 6a

Figure 6b

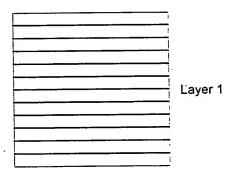
Vertical



Vertical



Vertical



Horizontal

Figure 6c

Figure 6d

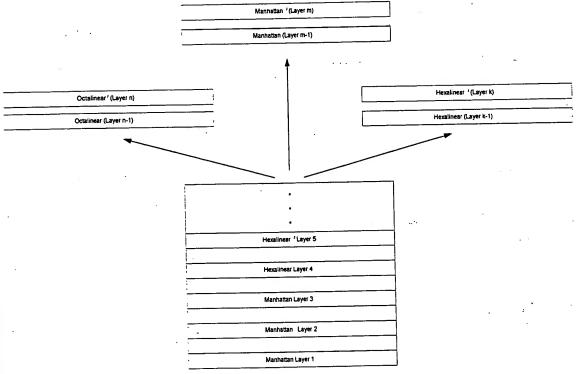


Figure 7

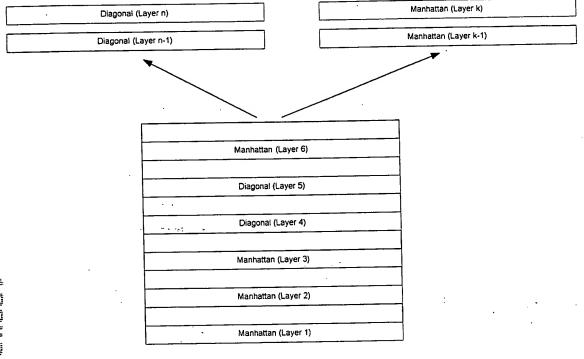


Figure 8



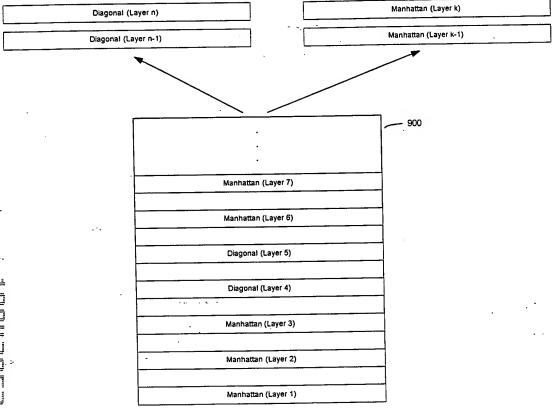


Figure 9

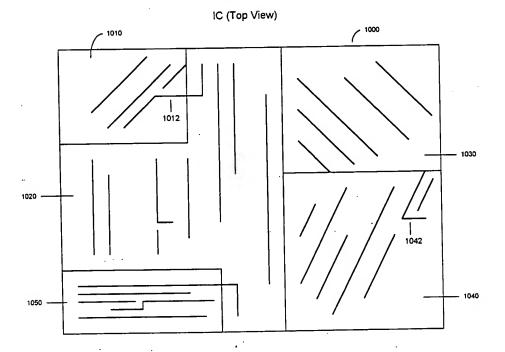


Figure 10

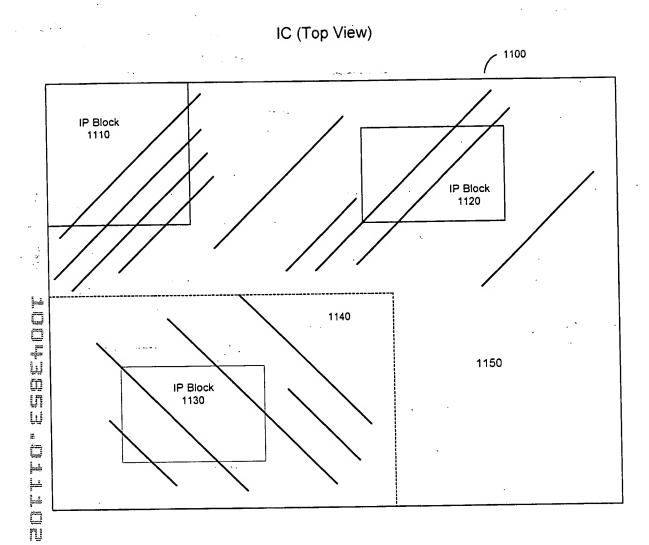


Figure 11

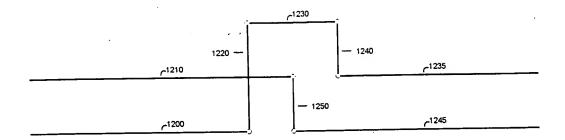


Figure 12a

Prior Art

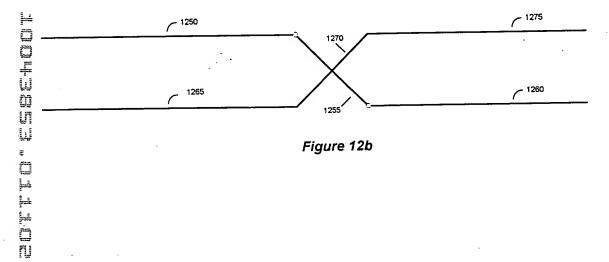
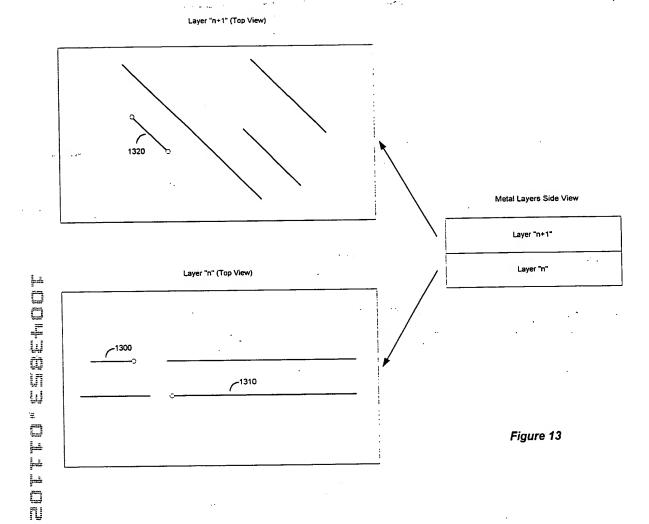


Figure 12b



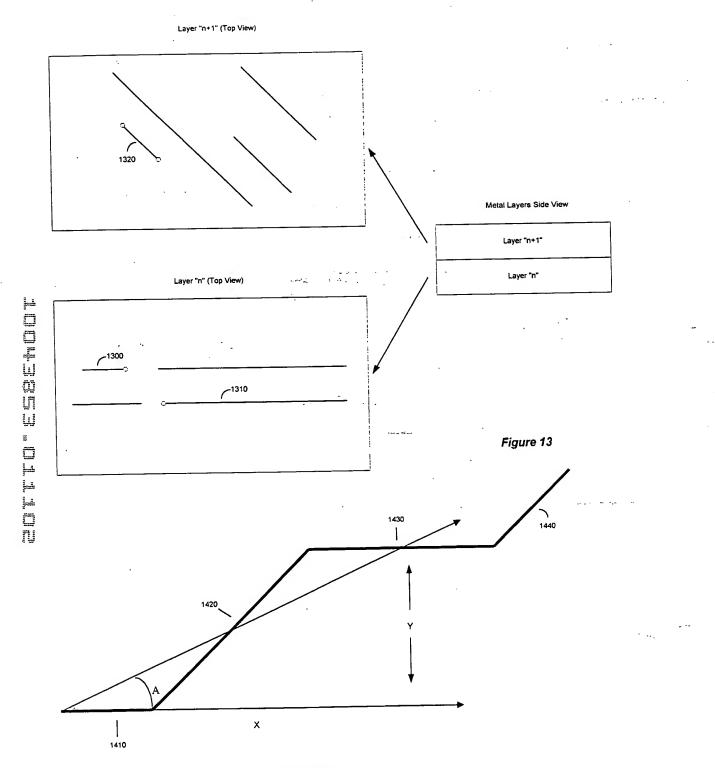


Figure 14

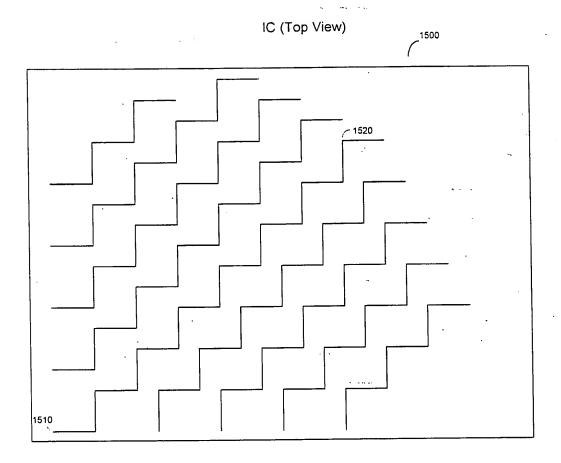


Figure 15

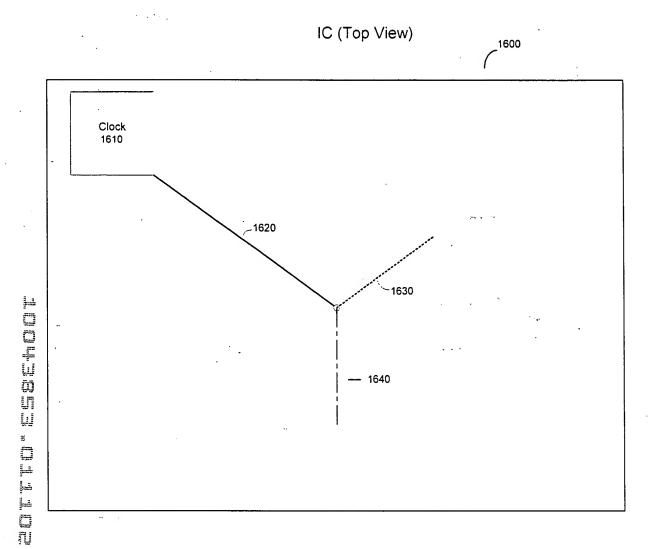


Figure 16